8-bit Proprietary Microcontroller смоз

F²MC-8L MB89560A Series

MB89567A/567AC/P568/PV560

DESCRIPTION

The MB89560A series has been developed as a general-purpose version of the F²MC^{*1}-8L family consisting of proprietary 8-bit, single-chip microcontrollers.

In addition to a compact instruction set, the microcontroller contains a variety of peripheral functions such as I²C interface*², timers, 2 ch 8-bit PWM timers, 8/16-bit timer, 21-bit timebase timer, 8-bit PWC timer, 17-bit Watch prescaler, Watch-dog timer, High speed UART, 8-bit SIO, UART/SIO, LCD controller/driver (optional booster), Two type Programmable Pulse Generators (PPG), an A/D converter, and external interrupt.

*1 : F²MC stands for FUJITSU Flexible Microcontroller.

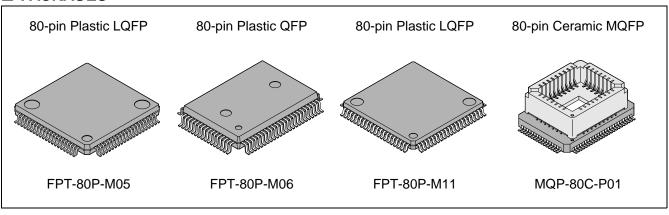
*2 : I²C of this product is complied to Intel Corp. System Management Bus Rev. 1.0 specification and to the Philips I²C specification.

■ FEATURES

- F²MC-8L family CPU core
- Low-voltage operation (when an A/D converter is not used)
- Low current consumption (applicable to the dual-clock system)
- Minimum execution time: 0.32 µs at 12.5 MHz /3.5 V to 5.5 V

PACKAGES







(Continued)

- I²C interface circuit
- LCD controller/driver: 24 segments x 4 commons (Max 96 pixels, duty LCD mode and Static LCD mode)
- LCD booster function (option)
- Wild register (Max 6 different address locations)
- 10-bit A/D converter: 8 channels
- Three types of Serial Interface:

High Speed UART (Transfer rate from 300 bps to 192000 bps /10 MHz main clock) 8-bit Serial I/O (SIO)

UART/SIO

- Two type of Programmable Pulse Generator(PPG): 6-bit PPG and 12-bit PPG
- Six types of timer
 - 8-bit PWM 2 channels timers
 - 8/16-bit timer/counter (8 bits x 2 channels or 16 bits x 1 channel)
 - 21-bit timebase timer
 - 8-bit PWC timer operation
 - 17-bit Watch prescaler
 - Watch-dog timer
- I/O ports: Max 50 channels
- External interrupt 1: 8 channels
- External interrupt 2 (wake-up function): 4 channels
- Low-power consumption modes (stop mode, sleep mode, and watch mode)
- LQFP-80 and QFP-80 package
- CMOS technology

■ PRODUCT LINEUP

Part number Parameter	MB89567A	MB89567AC	MB89P568	MB89PV560	
Classification	Mass production products (mask ROM products)		OTP	Piggy-back	
ROM size	32 K x (internal m	x 8-bit ask ROM)	48 K x 8-bit (internal PROM)	56 K x 8-bit (external ROM)	
RAM size		1 K x 8-bit		1 K x 8-bit	
CPU functions	Number of instructions: 136Instruction bit length: 8-bitInstruction length: 1 to 3 bytesData bit length: 1-, 8-, 16-bitMinimum execution time: 0.32 μs/12.5 MHzMinimum interrupt processing time: 2.88 μs/12.5 MHz				
Ports		General-purpose I/O ports (N-channel open drain): 20 pins (2 shared with I ² C inputs, 16 shared with LCD, 2 shared with othe resources) General-purpose I/O ports (CMOS) : 30 pins (shared with resources)			
21-bit timebase timer	21-bit Interrupt cycle: (2 ¹³ , 2 ¹⁵ , 2 ¹⁸ or 2 ²²)/Fсн ^{*7}				
Watchdog timer	Reset generate cycle: Min 2 ²¹ /FcH*7 for main clock, Min 2 ¹⁴ /FcL*7 for sub clock				
Watch prescaler	17-bit Interrupt cycle: 31.25 ms, 0.25 s, 0.50 s, 1.00 s, 2.00 s, 4.00 s/32.768 kHz for subclock				
8/16-bit timer/ counter	Can be operated either as a 2-channel 8-bit timer/counter (Timer 1 and Timer 2, each with its own independent operating clock cycle), or as one 16-bit timer/counter In Timer 1 or 16-bit timer/counter operation, event counter operation (external clock-triggered) and square wave output capable				
8-bit PWM 2 ch timer	 8-bit interval timer operation (square wave output capable, operating clock cycle: 1 tinst, 8 tinst, 16 tinst, 64 tinst) 8-bit resolution PWM operation (conversion cycle: 128 x 1 tinst to 256 x 64 tinst) 8/16-bit timer/counter output for counter clock selectability 				
PWC timer	 8-bit timer operation (count clock cycle: 1 tinst, 4 tinst, 32 tinst) 8-bit reload timer operation (toggle output possible, operating clock cycle: 1 to 32 tinst) 8-bit pulse width measurement (continuous measurement possible: H-width, L-width, rising edge to rising edge, falling edge to falling edge, and rising edge to falling edge) 				
10-bit A/D converter *2	10-bit resolution × 8 channels A/D conversion function (conversion time: 60 t _{inst}) Continuous activation by an 8/16-bit timer/counter output or a timebase timer output capable			e timer output capable.	
6-bit PPG	Internal 6-bit counter Pulse width and cycle are program selectable				
12-bit PPG	Internal 12-bit counter Pulse width and cycle are program selectable				

(Continued)

Part number Parameter	MB89567A	MB89567AC	MB89P568	MB89PV560		
I ² C interface* ⁴	Not Available		1 channel			
High speed UART	Transfer rate (300 bps	Transfer data length: 4-, 6-, 7-, 8-bit Transfer rate (300 bps to 192000 bps /9.216 MHz main clock) support sub-clock mode				
UART/SIO	5	′-, 8-bit for UART, 8-bit s to 78125 bps / 10 MH le				
8-bit serial I/O	8-bit, LSB first/MSB first Transfer clocks (one e		e internal shift clocks: 2 t	tinst, 8 tinst, 32 tinst) *5		
LCD	Common output: 4 (Max) Segment output: 24 (Max) LCD driving power (bias) pins: 4 LCD display RAM size: 12 bytes (24 × 4 bits, Max 96 pixels) Duty LCD mode and Static LCD mode Booster for LCD driving: option* ¹ Dividing resistor for LCD driving: option					
Wild register	Maximum of 6-byte data can be assigned in 6 different address. Used to replace any data in the ROM when specific address and data are assigned in Wild register. Wild register can be set up by using different communication methods through the device.					
External interrupt 1 (wake-up function)	8 independent channels (interrupt vector, request flag, request output enable) Edge selectability (rising/falling) Used also for wake-up from stop/sleep mode. (edge detection is also permitted in stop mode.)					
External interrupt 2 (wake-up function)	4 channels ("L" level interrupts, independent input enable). Used also for wake-up from stop/sleep mode. (Low-level detection is also permitted in stop mode.)					
Standby mode	Sub clock mode, sleep mode, stop mode and clock mode					
Process	CMOS					
Operating voltage *6	2.2 V to 5.5 V 2.7 V to 5.5 V 2.7 V to 5.5 V*3					

*1 : When booster is used, the bias is reduced by 1/3. It can be selected by mask option.

*2 : Voltage varies with product.

*3 : When external ROM is used, EPROM: MBM27C512-20 should be used, the operating voltage: 4.5 V to 5.5 V.

*4: I²C is complied to Intel Corp. System Management Bus Rev. 1.0 specification and to the Philips I²C specification.

*5 : 1 t_{inst} = one instruction cycle (execution time) which can be selected as 1/4, 1/8, 1/16, or 1/64 of main clock if main clock mode is selected, or 1/2 of the subclock if subclock mode is selected.

*6 : Varies with conditions such as the operating frequency. (See "ELECTRICAL CHARACTERISTICS.")

*7 : FCH : main clock source oscillation, FcL : sub clock source oscillation

PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89567A MB89567AC	MB89P568-101 MB89P568-102	MB89PV560-101 MB89PV560-102
FPT-80P-M05	0	0	X
FPT-80P-M06	0	0	X
FPT-80P-M11	0	0	X
MQP-80C-P01	Х	X	0

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the OTPROM (one-time PROM) products, verify its differences from the product that will actually be used. Take particular care on the following points:

• The stack area, etc., is set at the upper limit of the RAM.

2. Current Consumption

- For the MB89PV560, add the current consumed by the EPROM mounted in the piggy-back socket.
- When operating at low speed, the current consumed by the one-time PROM product is greater than that for the mask ROM product. However, the current consumption is roughly the same in sleep or stop mode.
- For more information, see " ELECTRICAL CHARACTERISTICS."

3. Mask Options

The functions available as options and the method of specifying options differ between products. Before using options check " MASK OPTIONS."

4. Wild register function

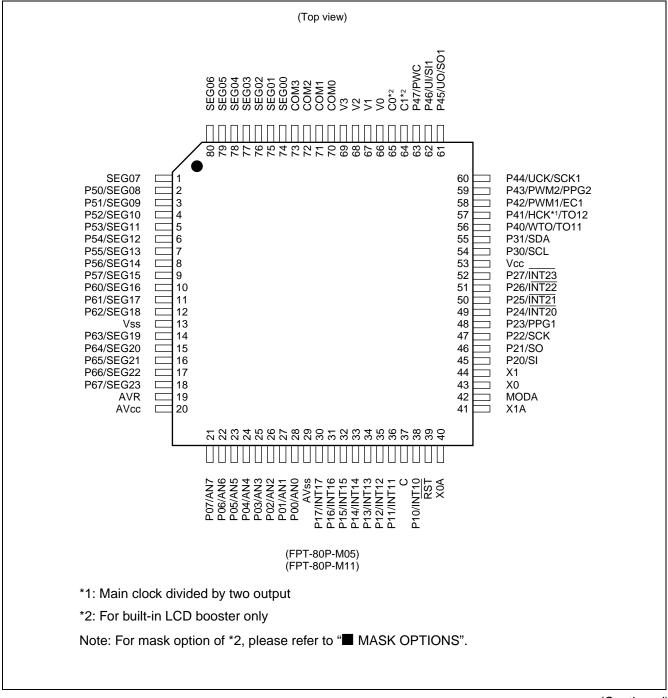
The Wild Register can be used in the following address spaces.

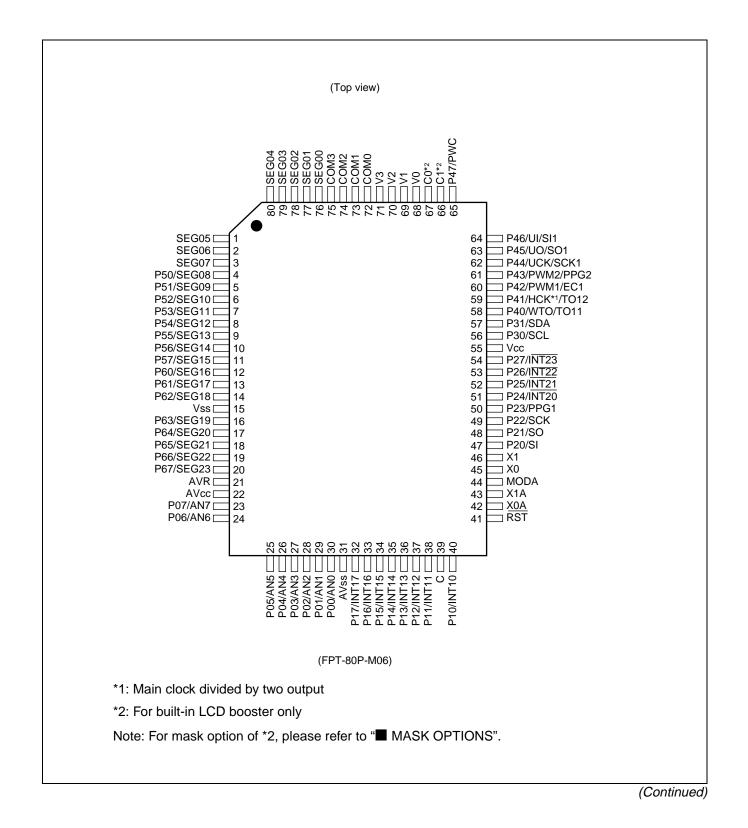
Device	Address Space
MB89PV560	4000н to FFFFн
MB89P568	4000н to FFFFн
MB89567A/567AC	8000н to FFFFн

5. P40, P41

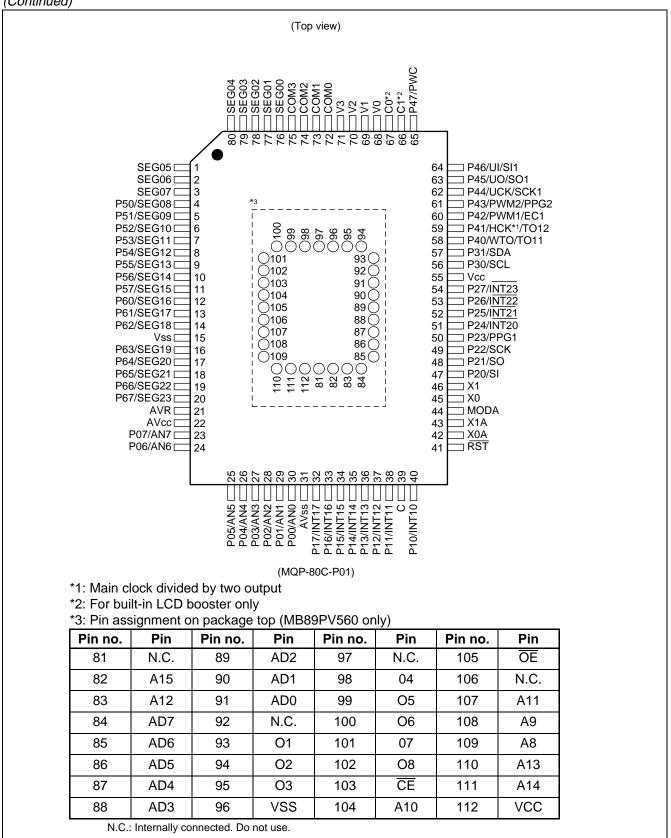
It will take about 64 count clock of external oscillation to initialize P40 and P41 pins in MB89PV560/P568. Therefore, these ports will be unstable for a while during power-on. For MB89567A/567AC, these ports will be in High-Z during power-on.

■ PIN ASSIGNMENT





(Continued)



Note: For mask option of *2, please refer to "MASK OPTIONS".

■ PIN DESCRIPTION

Pin no.			10		
LQFP ^{*1} LQFP ^{*2}	MQFP ^{*3} QFP ^{*4}	Pin name	I/O circuit type	Function	
43	45	X0		Crystal or other resonator connector pins for the main clock.	
44	46	X1	A	The external clock can be connected to X0. When this is done, be sure to leave X1 open.	
42	44	MODA	С	Memory access mode setting pins. Connect directly to VSS. Hysteresis input type.	
39	41	RST	D	Reset I/O pin This pin is a CMOS output type with a pull-up resistor, and a hysteresis input type. "L" is output from this pin by an internal reset request (optional). The internal circuit is initialized by the input of "L".	
49 to 52	51 to 54	P24/INT20 to P27/INT23	E	General-purpose CMOS I/O ports Also serve as an external interrupt 2 input (wake-up function). External interrupt 2 input is hysteresis input. Selectable pull-up resistor.	
30 to 36, 38	32 to 38, 40	P10/INT10 to P17/INT17	E	General-purpose CMOS I/O ports Also serve as input for external interrupt 1 input. External interrupt 1 input is hysteresis input. Selectable pull-up resistor.	
60	62	P44/UCK/ SCK1	E	General-purpose CMOS I/O ports Also serve as the clock I/O for the High-speed UART and Serial I/O. The peripheral is a hysteresis input type. Selectable pull-up resistor.	
61	63	P45/UO/ SO1	F	General-purpose CMOS I/O ports Also serves as the data output for the High-speed UART and Serial I/O.	
62	64	P46/UI/SI1	G	N-ch open drain general-purpose I/O ports Also serves as the data input for the High-speed UART and Serial I/O. The peripheral is a hysteresis input type.	
63	65	P47/PWC	G	N-ch open drain general-purpose I/O port Also serve as the external clock input for PWC. The peripheral is a hysteresis input.	
56	58	P40/WTO/ TO11	F	General-purpose CMOS I/O port Also serves as an 8/16-bit timer/counter output and PWC output.	

Pin no.					
LQFP ^{*1} LQFP ^{*2}	MQFP ^{*3} QFP ^{*4}	Pin name	I/O circuit type	Function	
57	59	P41/HCK/ TO12	F	General-purpose CMOS I/O port Also serves as an 8/16-bit timer/counter output. and half of main clock output Selectable pull-up resistor.	
45	47	P20/SI	Е	General-purpose CMOS I/O port Also serves as the data input for the serial I/O. The peripheral is a hysteresis input type. Selectable pull-up resistor.	
46	48	P21/SO	F	General-purpose CMOS I/O port Also serves as the data output for the serial I/O. Selectable pull-up resistor.	
47	49	P22/SCK	E	General-purpose CMOS I/O port Also serves as the clock I/O for the serial I/O. The peripheral is a hysteresis input type. Selectable pull-up resistor.	
48	50	P23/PPG1	F	General-purpose CMOS I/O port Also serves as the 6 bit PPG output pin. Selectable pull-up resistor.	
54	56	P30/SCL	G	N-ch open-drain general-purpose I/O port Clock I/O pin for I ² C interface	
55	57	P31/SDA	G	N-ch open-drain general-purpose I/O port Data I/O pin for I ² C interface	
65	67	C0		Function as capacitor connection pin in the products with a	
64	66	C1		booster.	
59	61	P43/ PWM2/ PPG2	F	General-purpose CMOS I/O port Also serves PWM wave output for the 8-bit PWM timer 1 and as 12 bit programmable pulse generator output. Selectable pull-up resistor.	
58	60	P42/ PWM1/ EC1	E	General-purpose CMOS I/O port Also serves as the PWM wave output and external clock for the 8/16 bit timer counter. Selectable pull-up resistor.	
21 to 28	23 to 30	P00/AN0 to P07/AN7	J	General-purpose CMOS I/O ports Also serve as the analog input for the A/D converter. Selectable pull-up resistor.	

(Continued)

Pin no.				
LQFP ^{*1} LQFP ^{*2}	MQFP ^{*3} QFP ^{*4}	Pin name	n name I/O circuit Function	
10 to 12 14 to 18	12 to 14 16 to 20	P60/ SEG16 to P67/ SEG23	н	N-ch open-drain general-purpose output ports Also serve as an LCD controller/driver segment output.
2 to 9	4 to 11	P50/SEG8 to P57/ SEG15	Н	N-ch open-drain general-purpose output ports Also serve as an LCD controller/driver segment output.
74 to 80, 1	1 to 3 76 to 80	SEG0 to SEG7	Ι	LCD controller/driver segment output-only pins
70 to 73	72 to 75	COM0 to COM3	I	LCD controller/driver common output-only pins
66 to 69	68 to 71	V0 to V3	_	LCD driving power supply pins.
40	42	X0A	ſ	Crystal or other resonator connector pins for the subclock
41	43	X1A	В	(Subclock: 32.768 kHz)
53	55	Vcc		Power supply pin
37	39	С		Capacitor connection pin *5
13	15	Vss		Power supply (GND) pin
20	22	AVcc		A/D converter power supply pin
19	21	AVR	—	A/D converter reference voltage input pin
29	31	AVss	_	A/D converter power supply pin Use this pin at the same voltage as Vss.

*1: FPT-80P-M05

*2: FPT-80P-M11

*3: MQP-80C-P01

*4: FPT-80P-M06

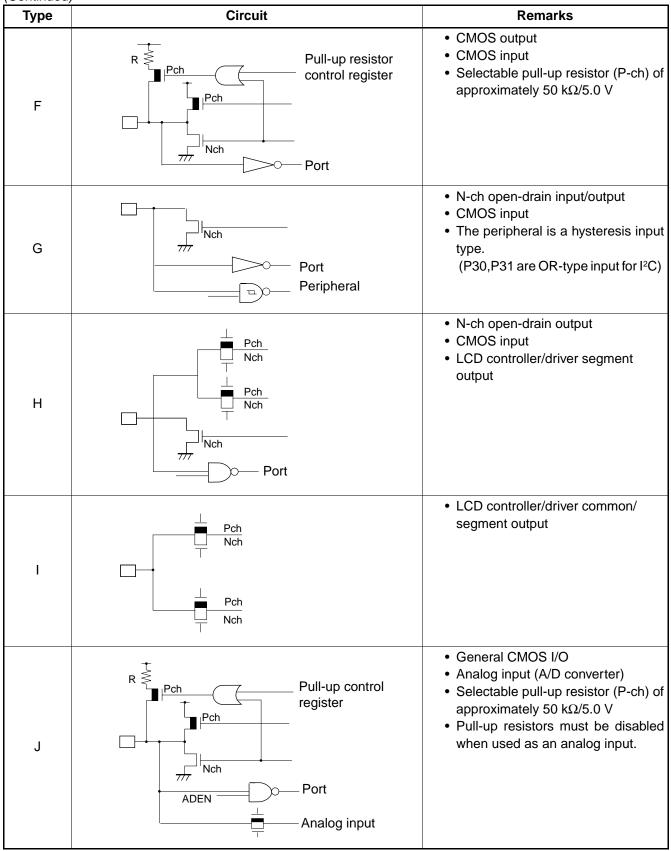
*5: When MB89567A / MB89567AC / MB89PV560-101 / MB89PV560-102 is used, this pin will become NC pin without internal connection. There is no problem to leave pins open, to fix pins at Vcc and to fix pins at Vss. When MB89P568-101 or MB89P568-102 is used, this pin must be connected to Vss.

Pin no.	Pin name	I/O	Function
82 83 84 85 86 87 88 89 90 91	A15 A12 A7 A6 A5 A4 A3 A2 A1 A0	Ο	Address output pins
93 94 95	01 02 03	I	Data input pins
96	Vss	0	Power supply (GND) pin
98 99 100 101 102	O4 O5 O6 O7 O8	I	Data input pins
103	CE	0	ROM chip enable pin Outputs "H" during standby.
104	A10	0	Address output pin
105	OE/V _{pp}	0	ROM output enable pin Outputs "L" at all times.
107 108 109	A11 A9 A8	0	Address output pins
110	A13	0	
111	A14	0	
112	Vcc	0	EPROM power supply pin
81 92 97 106	N.C.		Internally connected pins Be sure to leave them open.

• For External EPROM Socket (MB89PV560 ONLY)

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
A	X1 Nch Pch X0 Pch Nch Nch Nch Main clock control signal	 Main clock (main clock crystal oscillator) At an oscillation feedback resistor of approximately 1 MΩ/5.0 V
В	X1A Nch Pch X0A Nch Pch Nch Nch Nch Nch Sub clock control signal	 Subclock (subclock crystal oscillator) At an oscillation feedback resistor of approximately 4.5 MΩ/5.0 V
С		Hysteresis input
D	R Pch Nch 777	 CMOS output Hysteresis input At an output pull-up resistor (P-ch) of approximately 50 kΩ/5.0 V
E	Pull-up control register	 CMOS output CMOS input The peripheral is a hysteresis input type. Selectable pull-up resistor (P-ch) of approximately 50 kΩ/5.0 V
		(Continued)



HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than Vcc or lower than Vss is applied to input and output pins other than medium- to high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in " ELECTRICAL CHARACTERISTICS" is applied between Vcc and Vss.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AV $_{cc}$ and AVR) and analog input from exceeding the digital power supply (V $_{cc}$) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AVcc = DVcc = Vcc and AVss = AVR = Vss even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset and wake-up from stop mode.

7. Unused LCD dedicated pins

When LCD dedicated pins are not in use, keep it open.

8. Ports shared with SEG pin

When using port shared with SEG pin, be sure that the input voltage to port does not exceed the voltage of V3 (SEG driving voltage). This is particularly important to those devices with booster. When power-on or reset, SEG pin will output an initial value of "L".

9. LCD not in use

When LCD is not in use, connect the V3 pin to Vcc and keep other LCD dedicated pins open.

10. Wild Register function

In MB89PV560, wild register function cannot be evaluated. To evaluate the wild register function, use MB89P568.

11. Programming operation on RAM

Program operation debugging at RAM is not possible even when using MB89PV560.

12. Note to Noise in the External Reset Pin (RST)

If the reset pulse applied to the external reset pin (\overline{RST}) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (\overline{RST}).

■ PROGRAMMING TO THE EPROM ON THE MB89P568

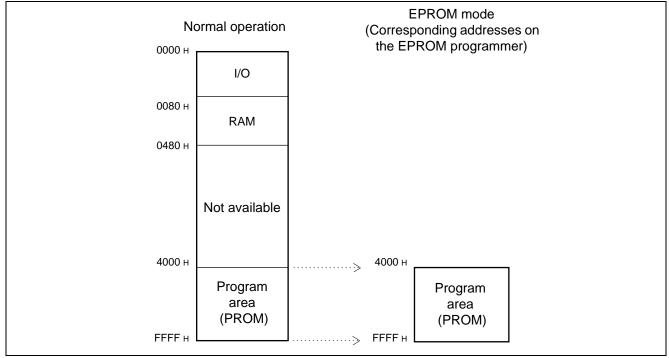
The MB89P568 is an OTPROM version of the MB89567A and MB89567AC.

1. Features

- 48-Kbyte PROM on chip
- Equivalency to the MBM27C1001 in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in EPROM mode is diagrammed below.



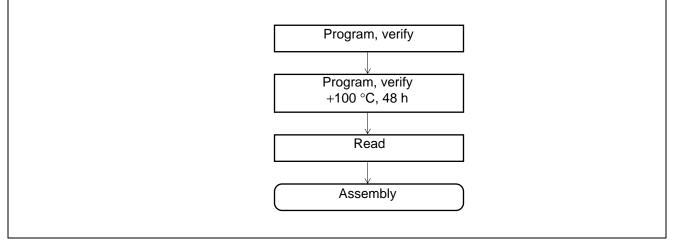
3. Programming to the EPROM

In EPROM mode, the MB89P568 functions equivalent to the MBM27C1001. This allows the PROM to be programmed with a general-purpose EPROM programmer (the electronic signature mode cannot be used) by using the dedicated socket adapter.

- Programming procedure
- (1) Set the EPROM programmer to the MBM27C1001.
- (2) Load program data into the EPROM programmer at 4000 μ to FFFF μ
- (3) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. EPROM Programmer Socket Adapter

Package	Compatible socket adapter
FPT-80P-M05	ROM-80SQF-32DP-8LA
FPT-80P-M06	ROM-80QF-32DP-8LA2
FPT-80P-M11	ROM-80QF2-32DP-8LA2

Inquiry: San Hayato Co., Ltd.: FAX +81-3-5396-9106 (Tokyo)

■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C512-20TV

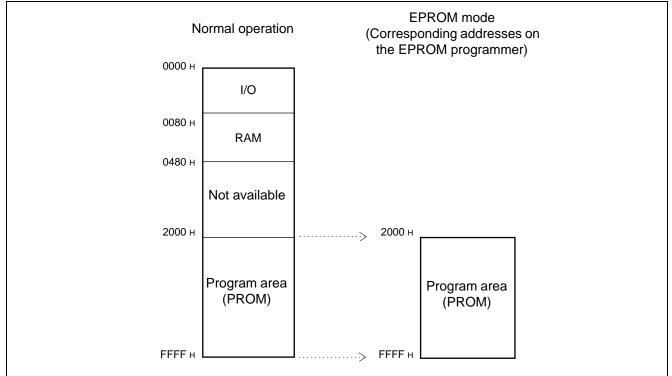
2. Programming Socket Adapter

To program to the PROM using an EPROM programmer, use the socket adapter (manufacturer: Sun Hayato Co., Ltd.) listed below.

Package	Adapter socket part number
LCC-32 (Rectangle)	ROM-32LC-28DP-YG

Inquiry: San Hayato Co., Ltd.: FAX +81-3-5396-9106 (Tokyo)

3. Memory Space

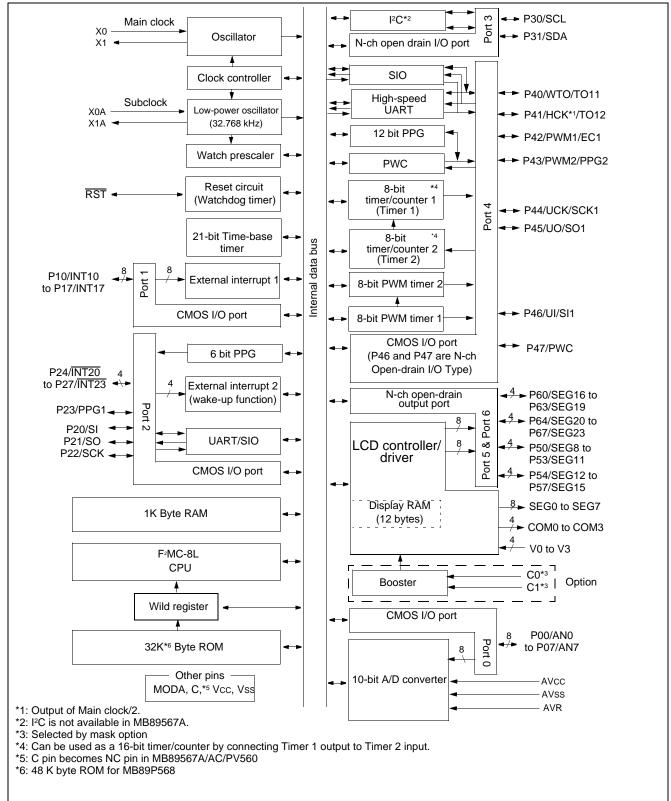


4. Programming to EPROM

(1) Set the EPROM programmer to the MBM27C512.

- (2) Load program data into the EPROM programmer at 2000H to FFFFH.
- (3) Program to 2000H to FFFFH with the EPROM programmer.

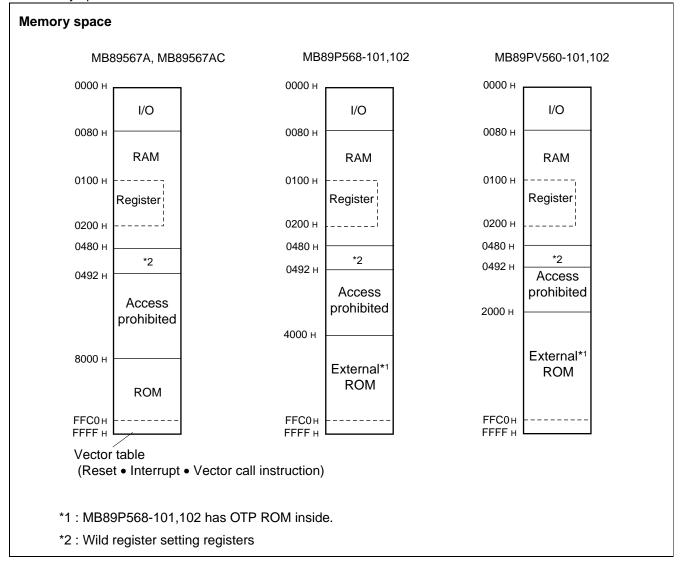




CPU CORE

1. Memory Space

The microcontrollers of the MB89560A series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89560A series is structured as illustrated below.



2. Registers

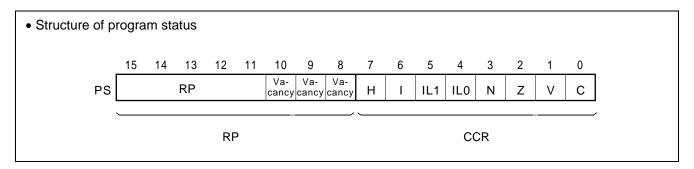
The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following registers are provided:

Program counter (PC)	: A 16-bit register for indicating specifies instruction storage positions.
Accumulator (A)	: A 16-bit temporary register for storing arithmetic operations, etc. When the
	instruction is an 8-bit data processing instruction, the lower byte is used.
Temporary accumulator (1	T): A 16-bit register which performs arithmetic operations with the accumulator when
	the instruction is an 8-bit data processing instruction, the lower byte is used.
Index register (IX)	: A 16-bit register for index modification
Extra pointer (EP)	: A 16-bit pointer for indicating a memory address
Stack pointer (SP)	: A 16-bit register for indicating a stack area
Dragram status (DC)	· A 1C bit register for staring a register pointer a condition code

Program status (PS) : A 16-bit register for storing a register pointer, a condition code

16 bits	l.	nitial value
P C	: Program counter	FFFDH
A	: Accumulator	Undefined
Т	: Temporally accumulator	Undefined
IX	: Indexing register	Undefined
EP	: Extra pointer	Undefined
SP	: Stuck pointer	Undefined
P S	: Program status	I Flag = 0, IL1, $0 = 11$ other bits are undefined.

The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.

Rule for Conversion of Actual	Addr	esse	s of	the C	Gene	eral-p	urpo	se R	egis	ter A	rea					
										RI	P Up	per			ation ower	Code
	"0"	"0"	"0"	"0"	"0"	"0"	"0"	"1"	R4	R3	R2	R1	R0	b2	b1	b0
	\downarrow	\downarrow														
Generated address	A15	A14	A13	A12	A11	A10	A9	A8	A7	A6	A5	A4	A3	A2	A1	A0

The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

- H-flag : Set when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared otherwise. This flag is for decimal adjustment instructions.
- I-flag: Interrupt is allowed when this flag is set to 1. Interrupt is prohibited when the flag is set to 0. Set to 0 when reset.
- IL1, 0 : Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1	I	t
1	0	2	
1	1	3	Low = no interrupt

N-flag : Set if the MSB is set to 1 as the result of an arithmetic operation. Cleared when the bit is set to 0.

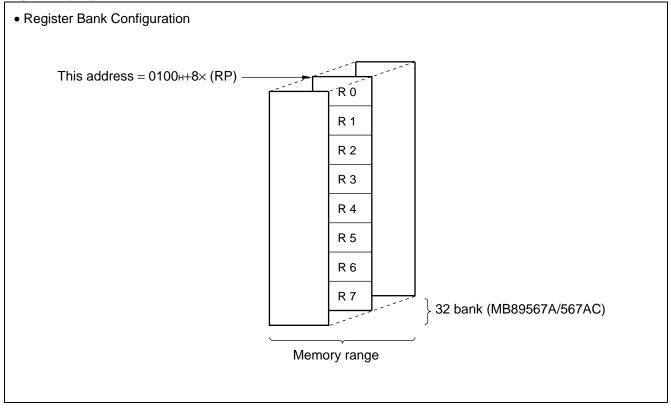
Z-flag : Set when an arithmetic operation results in 0. Cleared otherwise.

- V-flag : Set if the complement on 2 overflows as a result of an arithmetic operation. Reset if the overflow does not occur.
- C-flag : Set when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared otherwise. Set to the shift-out value in the case of a shift instruction.

The following general-purpose registers are provided :

General-purpose registers : An 8-bit resister for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers. Up to a total of 32 banks can be used. The bank currently in use is indicated by the register bank pointer (RP).



■ I/O MAP

Address	Register name	Register Description	Read/Write	Initial value
00н	PDR0	Port 0 data register	R/W	XXXXXXXXB
01н	DDR0	Port 0 data direction register	W	0000000в
02н	PDR1	Port 1 data register	R/W	XXXXXXXXB
03н	DDR1	Port 1 data direction register	W	0000000в
04н to 06н		(Vacancy)		
07н	SYCC	System clock control register	R/W	XXXMM100 _B
08н	STBC	Standby control register	R/W	00010ХХХв
09н	WDTC	Watchdog timer control register	W	0XXXXXXXB
0Ан	TBTC	Timebase timer control register	R/W	00ХХХ000в
0Вн	WPCR	Watch prescaler control register	R/W	00ХХ0000в
0Сн	PDR2	Port 2 data register	R/W	XXXXXXXXB
0Dн	DDR2	Port 2 data direction register	R/W	0000000в
0Ен	PDR3	Port 3 data register	R/W	XXXXXX11 _B
0 F н	PDR4	Port 4 data register	R/W	XXXXXXXXB
10н	DDR4	Port 4 direction register	R/W	ХХ00000в
11н	PDR5	Port 5 data register	R/W	0000000в
12н		(Vacancy)		
13н	PDR6	Port 6 data register	R/W	0000000в
14н to 19н		(Vacancy)		
1Ан	T2CR	Timer2 control register	R/W	Х00000Х0в
1Bн	T2DR	Timer2 data register	R/W	XXXXXXXXB
1Сн	T1CR	Timer1 control register	R/W	Х00000Х0в
1Dн	T1DR	Timer1 data register	R/W	XXXXXXXXB
1Eн to 21н		(Vacancy)		
22н	SMC11	UART1 mode control register 1	R/W	0000000в
23н	SRC1	UART1 mode data register	R/W	ХХ011000в
24н	SSD1	UART1 status/data register	R/W	00100Х1Хв
25н	SIDR1/SODR1	UART1 data register	R/W	XXXXXXXXB
26н	SMC12	UART1 mode control register 2	R/W	XX100001 _B
27н	CNTR1	PWM control register 1	R/W	0000000в
28н	CNTR2	PWM control register 2	R/W	000Х0000в
29н	CNTR3	PWM control register 3	R/W	X000XXXX _B
2Ан	COMR1	PWM compare register 1	W	XXXXXXXXB
2Вн	COMR2	PWM compare register 2	W	XXXXXXXXB
2Сн	PCR1	PWC pulse width control register 1	R/W	000XX000 _B

Address	Register name	Register Description	Read/Write	Initial value
2Dн	PCR2	PWC pulse width control register 2	R/W	0000000в
2Ен	RLBR	PWC reload buffer register	R/W	XXXXXXXX
2 F н	SMC21	UART2/SIO mode control register	R/W	0000000в
30н	SMC22	UART2/SIO mode control register 2	R/W	0000000в
31н	SSD2	UART2/SIO status/data register	R/W	00001XXX _B
32н	SIDR2/SODR2	UART2/SIO data register	R/W	XXXXXXXX
33н	SRC2	UART2/SIO rate control register	R/W	XXXXXXXX
34н	ADC1	A/D control register 1	R/W	Х00000Х0в
35н	ADC2	A/D control register 2	R/W	Х000001в
36н	ADDL	A/D data register L	R/W	XXXXXXXX
37н	ADDH	A/D data register H	R/W	XXXXXXXX
38н	RCR21	PPG control register 1(PPG2)	R/W	0000000в
39н	RCR23	PPG control register 3(PPG2)	R/W	0Х00000в
ЗАн	RCR22	PPG control register 2(PPG2)	R/W	XX000000B
3Вн	RCR24	PPG control register 4(PPG2)	R/W	XX000000B
3Cн to 3Eн		(Vacancy)		
3Fн	EIC1	External interrupt 1 control register 1	R/W	0000000в
40н	EIC2	External interrupt 1 control register 2	R/W	0000000в
41н	EIC3	External interrupt 1 control register 3	R/W	0000000в
42н	EIC4	External interrupt 1 control register 4	R/W	0000000в
43н to 50н		(Vacancy)		
51 н	IBSR	I ² C bus status register	R	0000000в
52н	IBCR	I ² C bus control register	R/W	0000000в
53н	ICCR	I ² C clock control register	R/W	000XXXXX _B
54н	IADR	I ² C address register	R/W	XXXXXXXXB
55н	IDAR	I ² C data register	R/W	XXXXXXXXB
56 H	EIE2	External interrupt 2 enable register	R/W	XXXX0000 _B
57н	EIF2	External interrupt 2 flag register	R/W	XXXXXXX0 _B
58 н	RCR1	PPG control register 1(PPG1)	R/W	0000000в
59 н	RCR2	PPG control register 2(PPG1)	R/W	0Х00000в
5Ан	CKR	Clock Output control register	R/W	0000000в
5В н	LCR1	LCD controller/driver control register 1	R/W	00010000в
5Сн	LCR2	LCD controller/driver control register 2	R/W	0000000в
5Dн	LCR3	LCD controller/driver control register 3	R/W	ХХ00000в
5Ен	LDR1	LCD data register 1	R/W	XXXXXXXX

(Continued)

Address	Register name	Register Description	Read/Write	Initial value
5 F н		(Vacancy)		
60н to 6Вн	VRAM	Display RAM	R/W	XXXXXXXXB
6Cн to 6Fн		(Vacancy)	I	
70н	SMR	Serial I/O mode register	R/W	0000000в
71н	SDR	Serial I/O data register	R/W	XXXXXXXXB
72н	PURR0	Pull-up resistor register 0	R/W	11111111в
73н	PURR1	Pull-up resistor register 1	R/W	11111111в
74 н	PURR2	Pull-up resistor register 2	R/W	11111111в
75н	PURR4	Pull-up resistor register 4	R/W	XX111111в
76н		(Vacancy)		
77н	WREN	Wild register enable register	R/W	ХХ00000в
78 н	WROR	Wild register data test register	R/W	ХХ00000в
79н	ADEN	A/D port input enable register	R/W	11111111в
7Ан		(Vacancy)	I	
7В н	ILR1	Interrupt level setting register 1	W	11111111в
7Сн	ILR2	Interrupt level setting register 2	W	11111111в
7Dн	ILR3	Interrupt level setting register 3	W	11111111в
7 Ен	ILR4	Interrupt level setting register 4	W	11111111в
7Fн	ITR	Interrupt test register	Access Prohibited	11111111в

Read/write access symbols

R/W : Readable and writable

R : Read-only

W : Write-only

Initial value symbols

0 : The initial value of this bit is "0".

1 : The initial value of this bit is "1".

X : The initial value of this bit is undefined.

 $\,M\,$: The initial value of this bit is determined by mask option.

Note : Do not use vacancies.

■ WILD REGISTER I/O MAP

Address	Register name	Register description	Read/Write	Initial value
480 H	WRARH1	Wild register high-byte address register1	R/W	XXXXXXXXB
481 н	WRARL1	Wild register low-byte address register1	R/W	XXXXXXXXB
482 H	WRDR1	Wild register data register1	R/W	XXXXXXXXB
483 н	WRARH2	Wild register high-byte address register2	R/W	XXXXXXXXB
484 H	WRARL2	Wild register low-byte address register2	R/W	XXXXXXXXB
485 H	WRDR2	Wild register data register2	R/W	XXXXXXXXB
486 H	WRARH3	Wild register high-byte address register3	R/W	XXXXXXXXB
487 н	WRARL3	Wild register low-byte address register3	R/W	XXXXXXXXB
488 H	WRDR3	Wild register data register3	R/W	XXXXXXXXB
489 н	WRARH4	Wild register high-byte address register4	R/W	XXXXXXXXB
48А н	WRARL4	Wild register low-byte address register4	R/W	XXXXXXXXB
48В н	WRDR4	Wild register data register4	R/W	XXXXXXXXB
48С н	WRARH5	Wild register high-byte address register5	R/W	XXXXXXXXB
48Dн	WRARL5	Wild register low-byte address register5	R/W	XXXXXXXXB
48 Ен	WRDR5	Wild register data register5	R/W	XXXXXXXXB
48F н	WRARH6	Wild register high-byte address register6	R/W	XXXXXXXXB
490 н	WRARL6	Wild register low-byte address register6	R/W	XXXXXXXXB
491 н	WRDR6	Wild register data register6	R/W	XXXXXXXXB

Read/write access symbols

- R/W : Readable and writable
- R : Read-only
- W : Write-only

Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.
- M : The initial value of this bit is determined by mask option.

Note : Do not use vacancies.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AVss = Vss = 0.0 V)

Devenuetor	Cumbal	Rat	ting	1.1	Domoska
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage	Vcc AVcc	Vss-0.3	Vss + 6.0	V	MB89567A, MB89567AC, MB89P568 and MB89PV560*1
	AVR	Vss-0.3	Vss + 6.0	V	AVR must not exceed "AVcc + 0.3V".
LCD power voltage	V0 to V3	Vss-0.3	Vss + 6.0	V	V0 to V3 should not exceed Vcc Without booster
Program voltage	Vpp	Vss-0.6	Vss+13.0	V	Only for the MB89P568
		Vss-0.3	Vcc + 0.3	V	For pins other than P30, P31, P46, P47, P50 to P57 and P60 to P67
Input voltage	Vı	Vss-0.3	Vcc + 0.3	V	P50 to P57, P60 to P67 Resister Ladder option
		Vss-0.3	V3	V	P50 to P57, P60 to P67 LCD booster option
		Vss-0.3	Vss + 6.0	V	For P30, P31, P46, P47
	Vo	Vss-0.3	Vcc + 0.3	V	For pins other than P30, P31, P46, P47, P50 to P57 and P60 to P67
Output voltage		Vss-0.3	Vcc + 0.3	V	P50 to P57, P60 to P67 Resister Ladder option
		Vss-0.3	V3	V	P50 to P57, P60 to P67 LCD booster option
		Vss-0.3	Vss + 6.0	V	For P30, P31, P46, P47
"L" level maximum output current	lol		15	mA	For pins other than P20 to P27
	IOL		30	mA	For P20 to P27 only
"L" level average output current	OLAV		4	mA	For pins other than P20 to P27*2
L level average output current	IOLAV		15	mA	For P20 to P27 only*2
"L" level total maximum output current	Σlol		100	mA	
"L" level total average output current	Σ Iolav		60	mA	*2
"H" level maximum output current	Іон		- 15	mA	For pins other than P20 to P27, P30, P31, P46, P47, P50 to P57, P60 to P67
			- 30	mA	For P20 to P27 only
"H" level average output current	Іонач		- 4	mA	For pins other than P20 to P27*2
There are age output current	IOHAV		- 15	III/A	For P20 to P27 only*2

(Continued)

(AVss = Vss = 0.0 V)Rating Symbol Parameter Unit Remarks Min Max "H" level total maximum output ∑Іон - 50 mΑ current "H" level total average output *2 \sum IOHAV - 30 mΑ current Power consumption \mathbf{P}_{D} 300 mW ____ ΤA °C Operating temperature + 85 - 40 Storage temperature - 55 + 150 °C Tstg

*1 : Use AVcc and Vcc set at the same voltage. Take care so that AVR does not exceed AVcc + 0.3 V, such as when power is turned on. Take care so that AVcc does not exceed Vcc, such as when power is turned on.

*2 : Average value (operating current × operating rate)

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

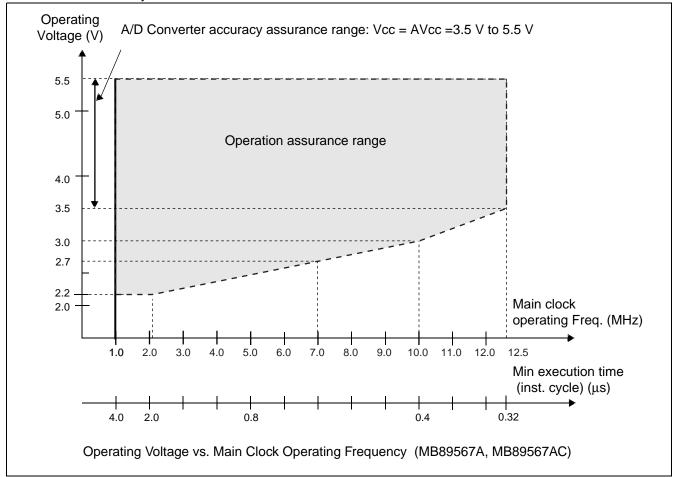
2. Recommended Operating Conditions

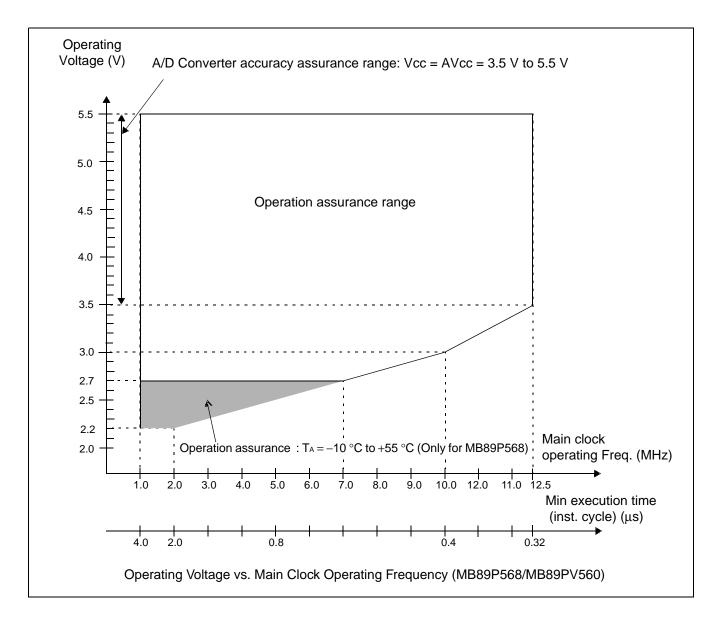
(AVss = Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
Farameter	Symbol	Min	Max	Unit	Remarks
		2.2*	5.5*	V	For MB89567A and MB89567AC
Dowor outpoly voltage	Vcc	1.5	5.5	V	Retains the RAM state in stop mode for MB89567A and MB89567AC
Power supply voltage	AVcc	2.7*	5.5*	V	For MB89PV560 and MB89P568
		1.5	5.5	V	Retains the RAM state in stop mode for MB89PV560 and MB89P568
LCD power voltage	V0 to V3	Vss	Vcc	V	Liquid crystal power supply range : without booster (The best value is according to the specification of LCD used.)
A/D converter reference input voltage	AVR	3.5	AVcc	V	
Operating temperature	TA	- 40	+ 85	°C	

* : These values depend on the operating conditions and the analog assurance range. See Figure "Operating Voltage vs. Main Clock Operating Frequency (MB89567A, MB89567AC)", "Operating Voltage vs. Main Clock Operating Frequency (MB89P568/MB89PV560)" and "6. A/D Converter Electrical Characteristics."

"Operating Voltage vs. Main Clock Operating Frequency (MB89567A, MB89567AC) and "Operating Voltage vs. Main Clock Operating Frequency (MB89P568/MB89PV560) indicate the operating frequency of the external oscillator at an instruction cycle of 4/FcH





Since the operating voltage range is dependent on the instruction cycle, see minimum execution time if the operating speed is switched using a gear.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

-		_ .			Value			40 °C to +85 °C)
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
	Vін	P00 to P07, P10 to P17, P20 to P27, P30 to P31, P40 to P45, P50 to P57, P60 to P67		0.7 Vcc	_	Vcc + 0.3	V	CMOS
"H" level input voltage	Vins	RST, MODA, INT10 to INT17, INT20 to INT23, SI,SCK,EC1,UCK, SCK1,UI,SI1,PWC		0.8 Vcc	_	Vcc+0.3	V	Hysteresis
	VIHSMB	SCL, SDA	_	Vss +1.4	_	Vss + 5.5	V	SMB input buffer selected
	VIHI2C			0.7 Vcc	_	Vss + 5.5	V	I ² C input buffer selected
	Vil	P00 to P07, P10 to P17, P20 to P27, P30 to P31, P40 to P45, P50 to P57, P60 to P67		Vss-0.3	_	0.3 Vcc	V	CMOS
"L" level input voltage	Vils	RST, MODA, INT10 to INT17, INT20 to INT23, SI,SCK,EC1,UCK, SCK1,UI,SI1,PWC	_	Vss-0.3	_	0.2 Vcc	V	Hysteresis
	VILSMB	SCL, SDA		Vss-0.3	_	Vss + 0.6	V	SMB input buffer selected
	VILI2C	SCL, SDA		Vss-0.3	_	0.3 Vcc	V	I ² C input buffer selected
Open-drain		P60 to P67, P50 to P57	_	Vss-0.3	_	Vcc + 0.3	V	Resister Ladder option
output pin application	Vd	P60 to P67, P50 to P57		Vss-0.3	_	V3	V	LCD booster option
voltage		P46, P47, P30, P31	_	Vss-0.3	_	Vss + 5.5	V	
"H" level output	Vон	P00 to P07, P10 to P17, P40 to P45	Іон = -2.0 mA	4.0	_	_	V	
voltage		P20 to P27	Іон = -15.0 mA	4.0	_	_	1	

3. DC Characteristics (power supply voltage : 5.0V) (AVcc = Vcc = 5.0 V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)

Deservator	Cumb al	Dim			Value				
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks	
"L" level output voltage	Vol	P00 to P07, P10 to P17, P30, P31, P40 to P47, P50 to P57, P60 to P67, RST	lo∟ = 4.0 mA	_	_	0.4	V		
		P20 to P27	lo∟= 15.0 mA			0.4			
Inputleakage		P00 to P07, P10 to P17, P20 to P27, P40 to P45	0.0 V < Vi < Vcc	- 5	_	+5	μΑ	Without pull-up Resistor	
current (High-Z output	n-Z l⊔ ut l⊔	P50 to P57, P60 to P67		- 5	_	+5	μA	Resistor Ladder option	
leakage current)		P50 to P57, P60 to P67	0.0 V < VI < V3	- 5	_	+5	μA	LCD booster option	
		MODA	0.0 V < Vı < Vcc	- 10	_	+10	μA	MB89PV560 MB89P568	
Open-drain		P50 to P57, P60 to P67	0.0 V < Vı < Vcc			+5	μΑ	Resistor Ladder option	
output leakage current	Iliod	ILIOD	P50 to P57, P60 to P67	0.0 V < Vı < V3	_	_	+5	μΑ	LCD booster option
current		P30, P31, P46, P47	0.0 V < VI < Vss + 5.5 V	_	_	+5	μA		
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P40 to P45, RST	Vı = 0.0 V	25	50	100	kΩ	When pull-up resistor selected except RST	
Pull-down resistance	Rmoda	MODA	Vi = 3.0 V	50	100	200	kΩ	MB89567A/ MB89567AC	
	lasi		$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 0.4 \ \mu s,$	_	15	20	– mA	MB89PV560 MB89P568	
	Icc1		Main clock run mode	_	8	13		MB89567A MB89567AC	
Powersupply	Icc2	Vec	$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 6.4 \ \mu s,$		5	8.5	– mA	MB89PV560 MB89P568	
current *1	1002	Vcc	Main clock run mode		1	3		MB89567A MB89567AC	
	Iccs1		$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 0.4 \ \mu s,$		5	7	– mA	MB89PV560 MB89P568	
	10031		Main clock sleep mode		2.5	5		MB89567A MB89567AC	

(AVcc = Vcc = 5.0 V, AVss = Vss = 0.0 V, $T_A = -40 \text{ °C to } +85 \text{ °C}$)

(Continued)

Demon	.	D:			Value			Barr
Parameter	Symbol	ol Pin	Condition	Min	Тур	Max	Unit	Remarks
	lasas		$F_{CH} = 10 \text{ MHz},$	_	1.5	3	m۸	MB89PV560 MB89P568
	Iccs ₂		t _{inst} *² = 6.4 μs, Sleep mode		0.7	2	mA	MB89567A MB89567AC
	Iccl		Fc∟ = 32.768 kHz,		3	7	mA	MB89PV560 MB89P568
	ICCL		Subclock mode, $T_A = +25 \ ^{\circ}C$	_	50	85	μΑ	MB89567A MB89567AC
Power supply current *1		Vcc	Fc∟ = 32.768 kHz,	_	30	50		MB89PV560 MB89P568
	Iccls		Subclock sleep mode, T _A = +25 °C	_	15	30	μA	MB89567A MB89567AC
			F _{CL} = 32.768 kHz,		5	15	μA	MB89PV560 MB89P568
	Ісст	T _A = +25 °C, Watch mode, Main clock stop mode	—	1.6	15	μΑ	MB89567A MB89567AC	
Power supply	Іссн	Vcc	$T_A = +25 ^{\circ}C,$		3	10	μA	MB89PV560 MB89P568
current *1	ICCH	VCC	Subclock stop mode	_	1	10	μΑ	MB89567A MB89567AC
LCD divided resistance	RLCD		Between Vcc and Vss	300	500	750	kΩ	
COM0 to COM3 output impedance	Rvсом	COM0 to COM3	V1 to V3 = 5.0 V	_	_	5	kΩ	
SEG0 to SEG23 output impedance	Rvseg	SEG0 to SEG23	V T 10 V 3 = 0.0 V	_	_	15	kΩ	
LCD controller/ driver leakage current	ILCDL	V0 to V3, COM0 to COM3, SEG0 to SEG23	_	- 1		1	μA	
Input capacitance	CIN	Other than AVcc, AVss, Vcc, and Vss	f = 1 MHz	_	10		pF	

*1 : The power supply current is measured at the external clock

*2 : For information on tinst, see "5. AC Characteristics (4) Instruction Cycle."

Note : For LCD and port multiplex pin (P50 to P57, P60 to P67), please refer to LCD specification when the port is used, and refer to LCD specification when used as LCD pin.

4. DC Characteristics (power supply voltage : 3.0V)

Parameter	Symbol	Pin	Condition	Vcc = 3.0V, AVss = Vss = 0.0 V, Value				
				Min	Тур	Max	Unit	Remarks
"H" level input voltage	Vін	P00 to P07, P10 to P17, P20 to P27, P30 to P31, P40 to P45, P50 to P57, P60 to P67		0.7 Vcc	_	Vcc + 0.3	V	CMOS
	Vінs	RST, MODA, INT10 to INT17, INT20 to INT23, SI,SCK,EC1,UCK, SCK1,UI,SI1,PWC		0.8 Vcc	_	Vcc + 0.3	V	Hysteresis
	VIHSMB	– SCL, SDA	_	Vss +1.4	_	Vss + 5.5	V	SMB input buffer selected
	VIHI2C		_	0.7 Vcc	_	Vss + 5.5	V	I ² C input buffer selected
"L" level input voltage	Vil	P00 to P07, P10 to P17, P20 to P27, P30 to P31, P40 to P45, P50 to P57, P60 to P67		Vss-0.3	_	0.3 Vcc	V	CMOS
	Vils	RST, MODA, INT10 to INT17, INT20 to INT23, SI,SCK,EC1,UCK, SCK1,UI,SI1,PWC		Vss-0.3	_	0.2 Vcc	V	Hysteresis
	VILSMB	- SCL, SDA	_	Vss - 0.3	_	Vss + 0.6	V	SMB input buffer selected
	VILI2C			Vss-0.3		0.3 Vcc	V	I ² C input buffer selected
Open-drain output pin application voltage	Vp	P60 to P67, P50 to P57		Vss-0.3	_	Vcc + 0.3	V	Resistor Ladder option
		P60 to P67, P50 to P57	_	Vss-0.3	_	V3	V	LCD booster option
		P46, P47, P30, P31		Vss-0.3	_	Vss + 5.5	V	
"H" level output voltage	Vон	P00 to P07, P10 to P17, P40 to P45	Іон = -2.0 mA	2.4	_	_	V	
		P20 to P27	Iон = -10 mA	2.4		_		

Demonster	0	D 1			Value	0.0 1, 1	11	Demoster
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
"L" level output voltage	Vol	P00 to P07, P10 to P17, P30, P31, P40 to P47, P50 to P57, P60 to P67, RST	IoL = 4.0 mA			0.4	V	
		P20 to P27	lo∟= 10 mA			0.4		
Inputleakage		P00 to P07, P10 to P17, P20 to P27, P40 to P45	0.0 V < VI < Vcc	-5	_	+5	μΑ	Without pull-up Resister
current (Hi-z output leakage	lu	P50 to P57, P60 to P67		-5	_	+5	μA	Resister Ladder option
current)		P50 to P57, P60 to P67	0.0 V < Vı < V3	-5	_	+5	μΑ	LCD booster option
		MODA	0.0 V < Vı < Vcc	-10		+10	μA	MB89PV560 MB89P568
Open-drain	Iliod	P50 to P57, P60 to P67	0.0 V < VI < Vcc	_	_	+5	μA	Resister Ladder option
output leakage current		age	P50 to P57, P60 to P67	0.0 V < Vı < V3	_	_	+5	μΑ
		P30, P31, P46, P47	0.0 V < VI < Vss + 5.5 V	_	_	+5	μΑ	
Pull-up resistance	Rpull	P00 to P07, P10 to P17, P20 to P27, P40 to P45, RST	V1 = 0.0 V	50	100	200	kΩ	When pull-up resistor selected except RST
Pull-down resistance	Rmoda	MODA	VI = 5.0 V	25	50	100	kΩ	MB89567A MB89567AC
	Icc1		$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 0.4 \ \mu s,$		6	10	m^	MB89PV560 MB89P568
Powersupply	ICC1		Main clock run mode		4	9	mA	MB89567A MB89567AC
current *1	la - :	Vcc	$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 6.4 \ \mu s,$		1.5	3	m ^	MB89PV560 MB89P568
	Icc2		Main clock run mode	—	0.4	2	mA	MB89567A MB89567AC

(AVcc = Vcc = 3.0V, AVss = Vss = 0.0V, T_A = -40 °C to +85 °C)

(Continued)

(Continued)

Demonstration	0	D '		5.0 V, AV	Value	- 0.0 v, I		°C to +85 °C)
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
			$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 0.4 \ \mu\text{s},$	_	2	4	– mA	MB89PV560 MB89P568
	ICCS1		Main clock sleep mode		1	3	- MA	MB89567A MB89567AC
	Iccs2		$F_{CH} = 10 \text{ MHz},$ $t_{inst}^{*2} = 6.4 \mu\text{s},$		1	2	– mA	MB89PV560 MB89P568
	10032		Main clock sleep mode		0.3	1.5		MB89567A MB89567AC
			Fc∟ = 32.768 kHz,		1	3	mA	MB89PV560 MB89P568
Power supply	lcc∟		Subclock mode, T _A = +25 °C	_	25	60	μA	MB89567A MB89567AC
current *1		Vcc FcL = 32.768 kHz,		_	15	30		MB89PV560 MB89P568
	Iccls		Subclock sleep mode , T _A = +25 °C	_	8	25	μA	MB89567A MB89567AC
			Fc∟ = 32.768 kHz,		5	15	μA	MB89PV560 MB89P568
	Ісст		T _A = +25 °C, Watch mode, Main clock stop mode	—	1	14	μΑ	MB89567A MB89567AC
	Іссн		T _A = +25 °C, Subclock stop mode	_	1	5	μA	
LCD divided resistance	RLCD	_	Between Vcc and Vss	300	500	750	kΩ	
COM0 to COM3 output impedance	Rvсом	COM0 to COM3	V1 to V3 = 3.0 V	_		5	kΩ	
SEG0 to 23 output impedance	Rvseg	SEG0 to SEG23	11010-0.01	_		15	kΩ	
LCD controller/ driver leakage current	ILCOL	V0 to V3, COM0 to COM3, SEG0 to SEG23	_	-1	_	1	μΑ	
Input capacitance	CIN	Other than AVcc, AVss, Vcc, and Vss	f = 1 MHz	_	10		pF	

*1 : The power supply current is measured at the external clock

*2 : For information on tinst, see "5. AC Characteristics (4) Instruction Cycle."

Note : For LCD and port multiplex pin (P50 to P57, P60 to P67), please refer to LCD specification when the port is used, and refer to LCD specification when used as LCD pin.

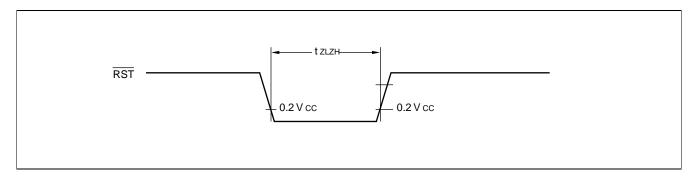
5. AC Characteristics

(1) Reset Timing

$(V_{CC} = 5.0 \text{ V}, \text{ AVss} = \text{Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C})$									
Parameter	Symbol	Condition	Valu	ae	Unit	Remarks			
Parameter	Symbol	Condition	Min	Мах	Unit	Remarks			
RST "L" pulse width	tzlzн	—	48 t HCYL		ns				

Notes : • there is the oscillation cycle (1/FeH) to input to the X0 pin.

 If the reset pulse applied to the external reset pin (RST) does not meet the specifications, it may cause malfunctions. Use caution so that the reset pulse less than the specifications will not be fed to the external reset pin (RST).



(2) Power-on Reset

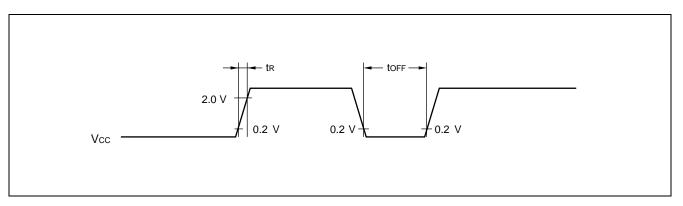
 $(AV_{SS} = V_{SS} = 0.0 \text{ V}, \text{ } T_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
Farameter	Symbol Condition		Min	Мах	Unit	Rellidiks
Power supply rising time	tR		0.5	50	ms	
Power supply cut-off time	toff		1		ms	Due to repeated operations

Note : Make sure that power supply rises within the selected oscillation stabilization time.

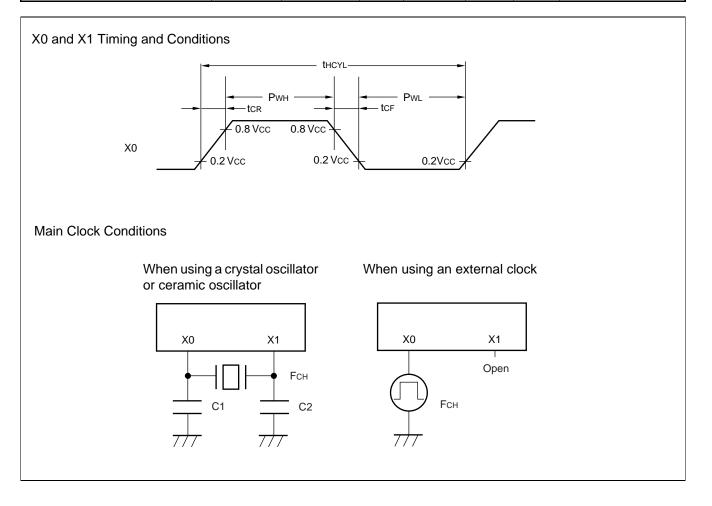
For example, when the main clock is operating at 10 MHz (F_{CH}) and the oscillation stabilization time select option has been set to 2¹⁸/F_{CH}, the oscillation stabilization delay time is 26.2 ms. Therefore, the maximum value of power supply rising time is about 26.2 ms.

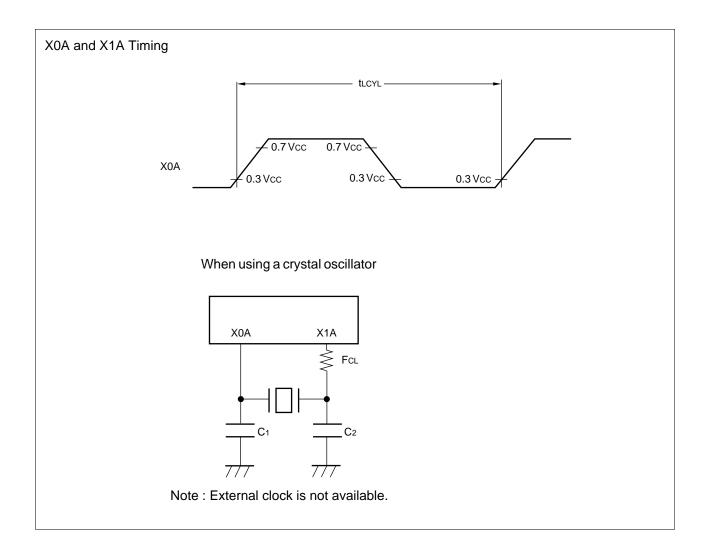
Rapid changes in power supply voltage may cause a power-on reset. If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.



(3) Clock Timing

				(AVss	s = Vss =	0.0 V, T	A = −40 °C to +85 °C)
Parameter	Symbol	Pin		Value		Unit	Remarks
Farameter	Symbol	ГШ	Min	Тур	Max	Unit	Remarks
Clock frequency	Fсн	X0, X1	1	—	12.5	MHz	Main clock
	Fc∟	X0A, X1A	_	32.768	—	kHz	Subclock
Clock cycle time	t HCYL	X0, X1	80	_	1000	ns	Main clock
	t LCYL	X0A, X1A	_	30.5	—	μs	Subclock
Input clock pulse width	Р _{WH} Рw∟	X0	20	—	_	ns	External clock
Input clock rising/falling time	tcr tcr	X0	_	_	10	ns	External clock





(4) Instruction Cycle

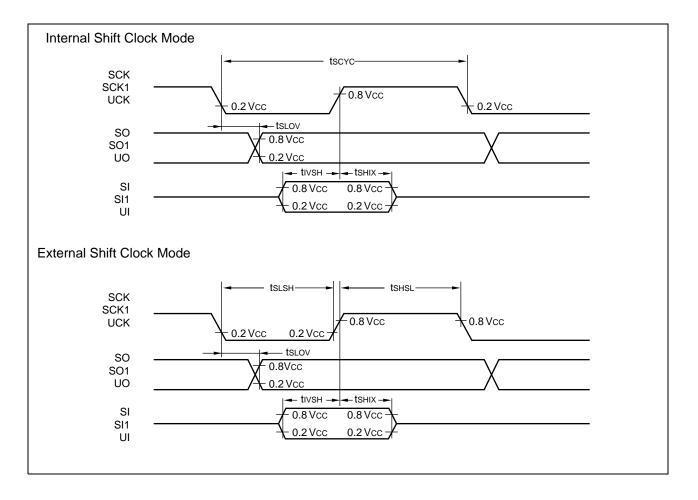
 $(AV_{SS} = V_{SS} = 0.0 \text{ V}, \text{ } \text{T}_{A} = -40 \text{ }^{\circ}\text{C} \text{ to } +85 \text{ }^{\circ}\text{C})$

Parameter	Symbol	Value	Unit	Remarks
Instruction cycle (minimum execution time)	+	4/Fсн, 8/Fсн, 16/Fсн, 64/Fсн	μs	t_{inst} = 0.32 µs when operating at FcH = 12.5 MHz (4/FcH)
	tinst -	2/FcL		t_{inst} = 61.036 μs when operating at FcL = 32.768 kHz

(5) Serial I/O Timing

		(Vo	cc = 5.0V, AVs	s = Vss=	0.0 V, T	A = -40	°C to +85 °C)
Parameter	Symbol	Pin	Condition	Val	ue	Unit	Remarks
Falameter	Symbol	FIII	Condition	Min	Max	Unit	Reina KS
Serial clock cycle time	tscyc	SCK, SCK1, UCK		2 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO, SCK1, SO1, UCK, UO		-200	+200	ns	
Valid SI $ ightarrow$ SCK \uparrow	tıvsн	SI, SCK, SI1, SCK1, UI, UCK	Internal shift clock mode	200	_	ns	
$SCK \uparrow \rightarrow valid SI hold time$	tsнix	SCK, SI, SCK1, SI1, UCK, UI		200	_	ns	
Serial clock "H" pulse width	t shsl	SCK SCK4 LICK		1 tinst*	_	μs	
Serial clock "L" pulse width	t s∟sн	SCK, SCK1, UCK		1 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO, SCK1, SO1, UCK, UO	External shift	0	200	ns	
Valid SI $ ightarrow$ SCK \uparrow	tıvsн	SI, SCK, SI1, SCK1, UI, UCK	clock mode	200	_	ns	
$SCK \uparrow \to valid SI hold time$	tsнix	SCK, SI, SCK1, SI1, UCK, UI		200	_	ns	

* : For information on tinst, see "(4) Instruction Cycle."

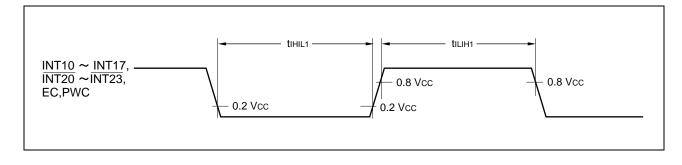


(6) Peripheral Input Timing

 $(Vcc = 5.0V, AVss = Vss = 0.0 V, T_A = -40 °C to +85 °C)$

Parameter	Symbol	Pin	Condition	Value		Unit	Remarks
Farameter	Symbol	FIII	Condition	Min	Max		itemai ka
Peripheral input "H" pulse width 1	t iliH1	INT10 to INT17,		2 tinst*	_	μs	
Peripheral input "L" pulse width 1	t iHi∟1	INT20 to INT23, EC, PWC		2 tinst*	_	μs	

*: For information on tinst, see "(4) Instruction Cycle."



(7) I²C timing

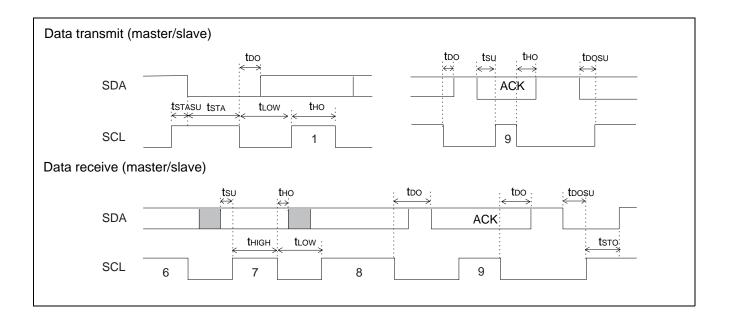
(7) FC timing				(Vcc = 5.0 V, A	Vss = Vss = 0.0 V, TA =	_40 °C	C to +85 °C)
Parameter	Symbol	Pin	Condition	Va	lue	Unit	Remarks
Farameter	Symbol	ГШ	Condition	Min	Мах	Unit	Neillai KS
Start condition output	t sta	SCL SDA		1/4 t _{inst} *1 × M*² x N*³ - 20	1/4 t _{inst} × M*² x N*³ + 20	ns	Master mode
Stop condition output	t sтo	SCL SDA		1/4 t _{inst} × (M* ² × N* ³ + 8) - 20	$1/4 \text{ t}_{inst} \times (M^{*2} \times N^{*3} + 8) + 20$	ns	Master mode
Start condition detect	t sta	SCL SDA	_	1/4 t _{inst} × 6 + 40	_	ns	
Stop condition detect	tsто	SCL SDA		1/4 t _{inst} × 6 + 40	_	ns	
Re-start condition output	t stasu	SCL SDA		1/4 t _{inst} × (M* ² × N* ³ + 8) - 20	$1/4 \text{ tinst} \times (M^{*2} \times N^{*3} + 8) + 20$	ns	Master mode
Re-start condition detect	t stasu	SCL SDA		1/4 t _{inst} × 4 + 40	_	ns	
SCL output LOW width	tLow	SCL		$1/4 t_{inst} \times M^{*2} \times N^{*3}$ - 20	$1/4 \text{ tinst} \times$ M* ² × N* ³ + 20	ns	Master mode
SCL output HIGH width	tніgн	SCL		1/4 t _{inst} × (M* ² × N* ³ + 8) - 20	$1/4 \text{ tinst} \times (M^{*2} \times N^{*3} + 8) + 20$	ns	Master mode
SDA output delay	tdo	SDA	_	1/4 t _{inst} × 4 - 20	1/4 t _{inst} × 4 + 20	ns	
SDA output setup time after interrupt	toosu	SDA		1/4 t _{inst} × 4 - 20	_	ns	*4
SCL input LOW pulse width	t LOW	SCL		$1/4 t_{inst} \times 6 + 40$	_	ns	
SCL input HIGH pulse width	tніgн	SCL		1/4 t _{inst} × 2 + 40	_	ns	
SDA input setup time	t su	SDA	—	40	—	ns	
SDA hold time	tно	SDA	—	0	—	ns	

*1 : For information in t_{inst}, see " (4) Instruction Cycle".

*2 : M is defined in the ICCR CS4 and CS3 (bit 4 to bit 3) . For details, please refer to the H/W manual register explanation.

 $^{\ast}3$: N is defined in the ICCR CS2 to CS0 (bit 2 to bit 0) .

*4 : When the interrupt period is greater than SCL "L" width, SDA and SCL output (Standard) value is based on hypothesis when rising time is 0 ns.



6. A/D Converter Electrical Characteristics

(1) For MB89567A/AC A/D Converter

		1	(AVcc	= 2.7 V to 5		= Vss = 0.0	V, Τ _Α	= −40 °C to +85 °C)	
Parameter	Symbol	Pin	Condition		Value	T	Unit	Remarks	
i ulullotoi	Cymbol		Condition	Min	Тур	Мах	onne	Romanio	
Resolution			—			10	bit		
Total error						±3.0	LSB	-	
Non-linearity error						±2.5	LSB	1LSB = AVR/1024	
Differential linearity error					_	_	±1.9	LSB	
Zero transition voltage	Vот		AVR=AVcc	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	mV		
Full-scale transition voltage	VFST			AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 1.5 LSB	mV		
Interchannel disparity				_	—	4	LSB	1LSB = AVR/1024	
A/D mode conversion time *3	_			_	60 tinst*1	_			
A/D Sampling time				_	16 tinst ^{*1}		μs		
Analog port input current	Iain	AN0		_	—	10	μA		
Analog input voltage	VAIN	to AN7		AVss	_	AVR	V		
Power supply	IA	AVcc	_	_	4	6	mA	when A/D conversion is activated	
current	Іан	AVCC	T _A = +25 °C		1	5	μΑ	when A/D conversion is stopped	
Reference voltage	_		_	AVss+3.5	_	AVcc	V		
Reference	IR	AVR	A/D is Activated	—	200	—	μA		
voltage supply current	Ігн		A/D is Stopped	—		5	μΑ	*2	

*1 : For information on t_{inst}, see "(4) Instruction Cycle" in "5. AC Characteristics."

*2 : When A/D conversion is not in operation, and the CPU is in STOP mode.

*3 : Included sampling time

(2) For MB89P568/PV560 A/D Converter

Denementen	Ourseland	D :			Value		11	Dementer
Parameter	Symbol	Pin	Condition	Min	Тур	Max	Unit	Remarks
Resolution			_	—	_	10	bit	
Total error				—		±3.0	LSB	1LSB =
Non-linearity error				—		±2.5	LSB	AVR/1024
Differential linearity error						±1.9	LSB	
Zero transition voltage	Vот		AVR=AVcc	AVss – 1.5 LSB	AVss + 0.5 LSB	AVss + 2.5 LSB	mV	
Full-scale transition voltage	VFST			AVR – 3.5 LSB	AVR – 1.5 LSB	AVR + 1.5 LSB	mV	
Interchannel disparity					_	4	LSB	1LSB = AVR/1024
A/D mode conversion time *3					60 tinst*1		μs	
A/D Sampling time	-			_	16 t inst*1	_		
Analog port input cur- rent	Iain	AN0 to			_	10	μA	
Analog input voltage	VAIN	AIN7		AVss		AVR	V	
	la	AVcc	_	_	4	6	mA	when A/D conversion is activated
Power supply current	Іан	AVCC	T _A = +25 °C	_	1	5	μΑ	when A/D conversion is stopped
Reference voltage	_		—	AVss + 3.5	—	AVcc	V	
Reference voltage	IR	AVR	A/D is Activated	_	400	_	μA	
supply current	Ігн		A/D is Stopped	_	_	5	μΑ	*2

*1 : For information on tinst, see "(4) Instruction Cycle" in "5. AC Characteristics."

 $^{\ast}2$: When A/D conversion is not in operation, and the CPU is in STOP mode.

*3 : Included sampling time

(3) A/D Converter Glossary

Resolution

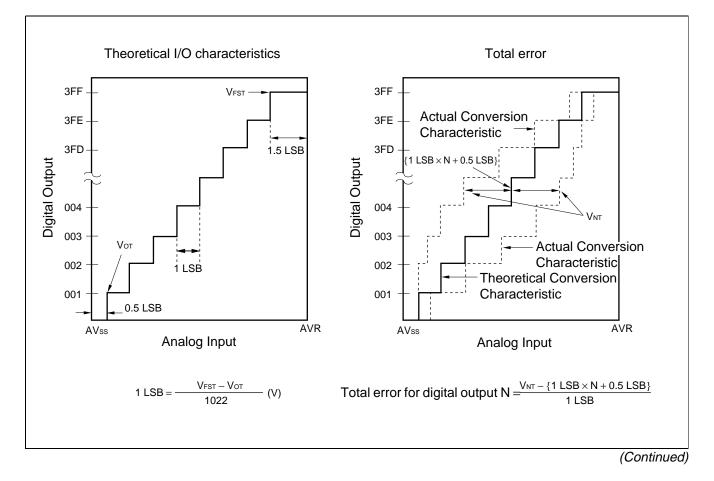
Analog changes that are identifiable with the A/D converter.

• Linearity error

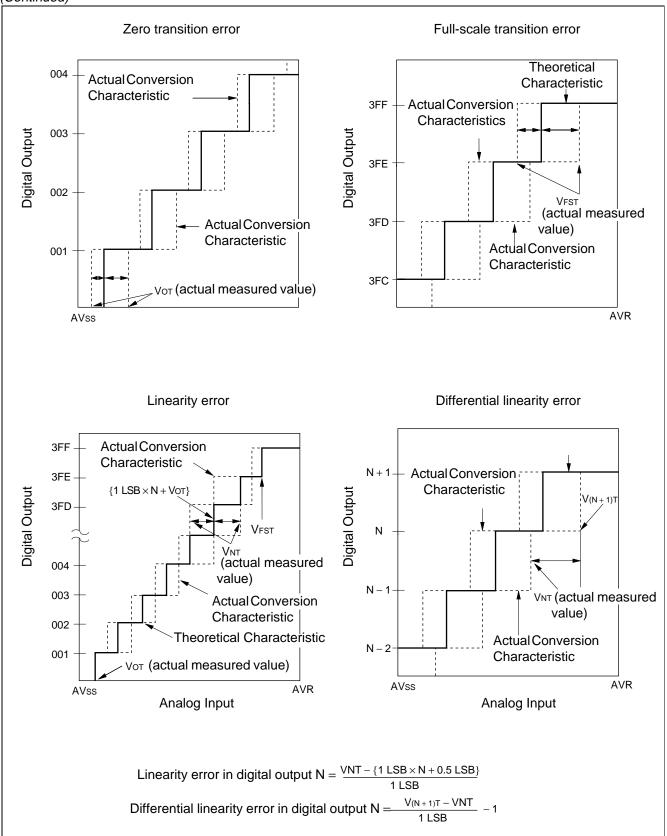
The deviation of the straight line connecting the zero transition point ("00 0000 0000" \leftrightarrow "00 0000 0001") with the full-scale transition point ("11 1111 1110" \leftrightarrow "11 1111 1111") from actual conversion characteristics

- Differential linearity error The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value
- Total error (unit: LSB)

The difference between theoretical and actual conversion values caused by the zero transition error, full-scale transition error, linearity error, quantization error, and noise

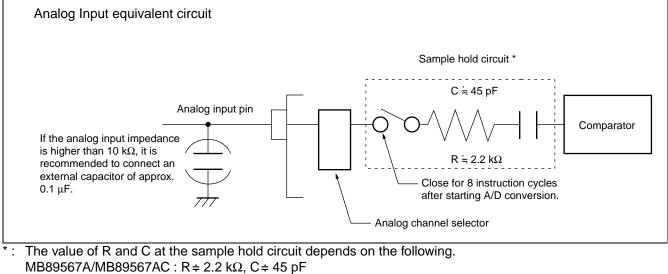






(4) Precautions

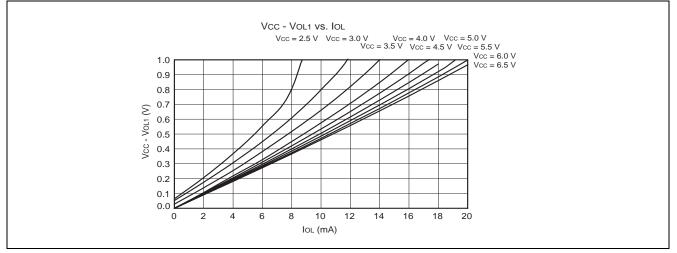
- The smaller the | AVR-AVss | is, the greater the error would become relatively.
- The output impedance of the external circuit for the analog input must satisfy the following conditions : Output impedance of the external circuit < Approx. 10 k Ω
- If the output impedance of the external circuit is too high, an analog voltage sampling time might be insufficient.



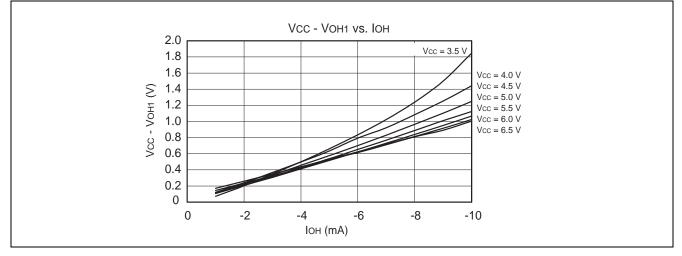
MB89P568/MB89PV560 : R ≑ 1.4 kΩ, C ≑ 64 pF

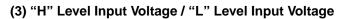
■ EXAMPLE CHARACTERISTICS

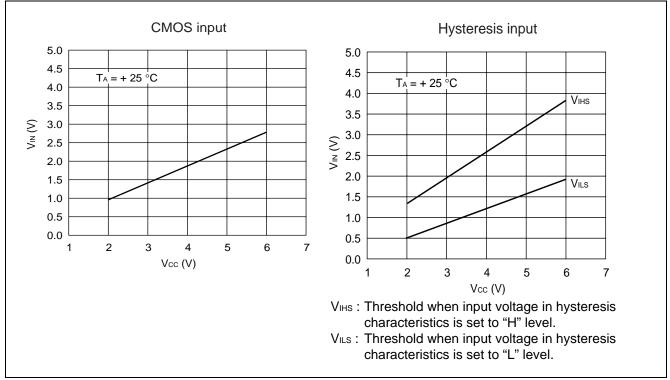
(1) "L" Level Output Voltage

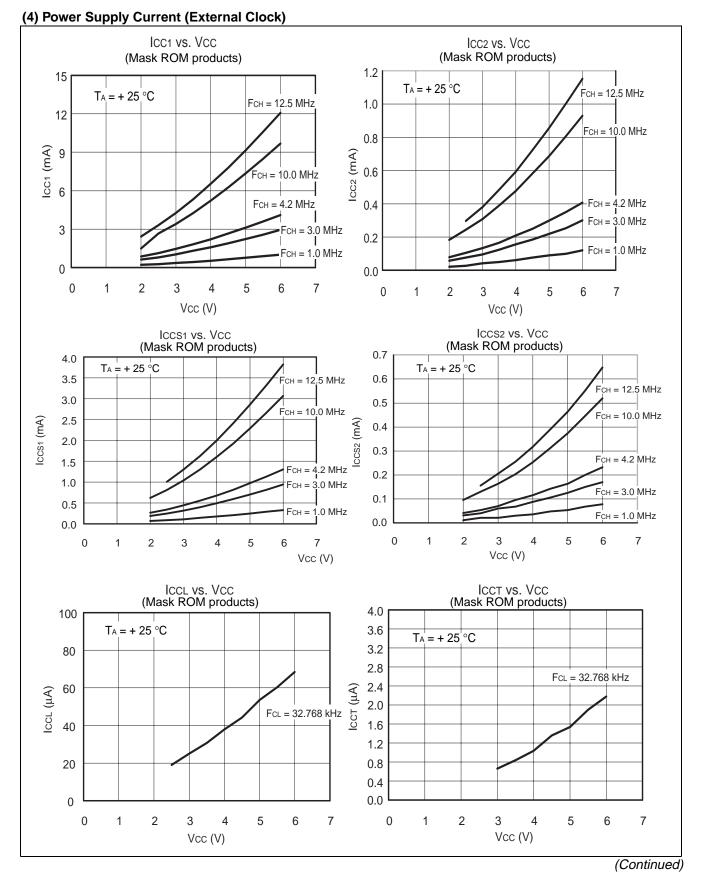


(2) "H" Level Output Voltage

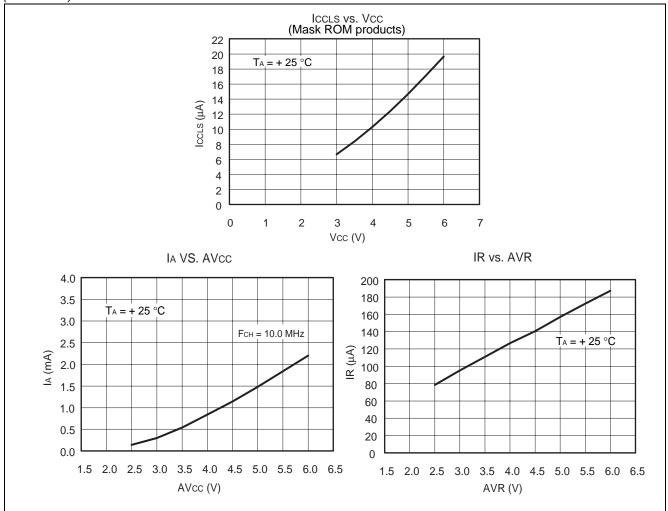




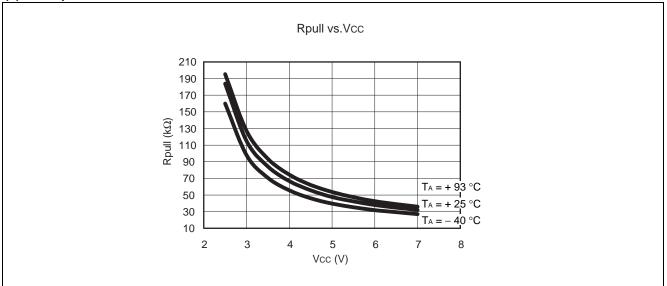




(Continued)



(5) Pull-up Resistance



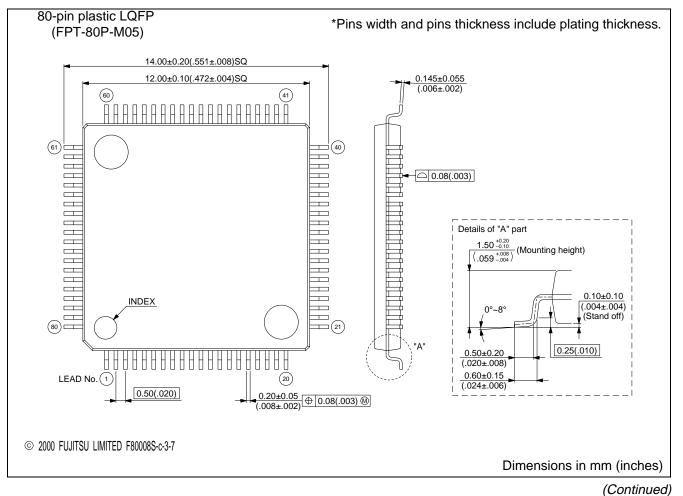
■ MASK OPTIONS

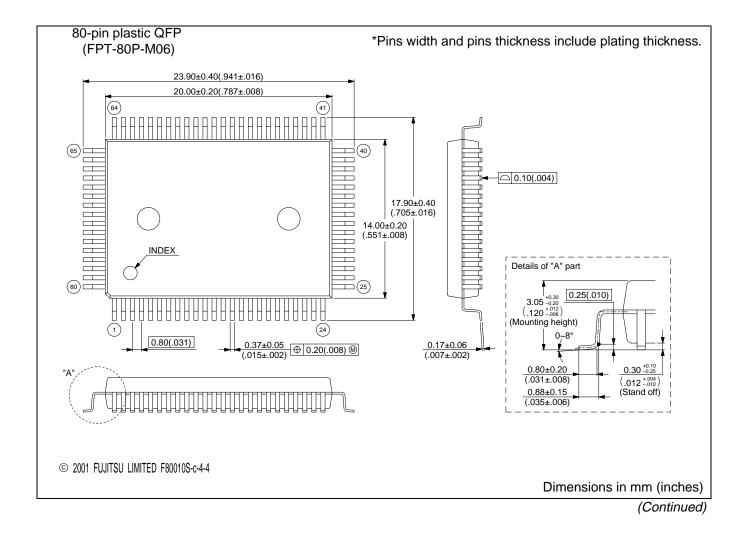
No.	Model	MB89567A MB89567AC	MB89P568	MB89PV560
NO.	Specification method	Specify when ordering mask.	Setting unavailable.	Setting unavailable.
1	Main clock oscillation stabilization delay time initial value* selection (Fcн = 10 MHz) • 01: 2 ¹⁴ /Fcн (Approx. 1.6 ms) • 10: 2 ¹⁷ /Fcн (Approx. 13.1 ms) • 11: 2 ¹⁸ /Fcн (Approx. 26.2 ms)	Selectable	2 ¹⁸ /F _{CH} (Approx. 26.2 ms)	2¹ଃ/Fсн (approx. 26.2 ms)
2	 LCD driving power supply On-chip voltage booster Internal voltage divider (external divider resistors can be used) 	Selectable	-101 Internal voltage divider -102 On-chip voltage booster	-101 Internal voltage divider -102 On-chip voltage booster

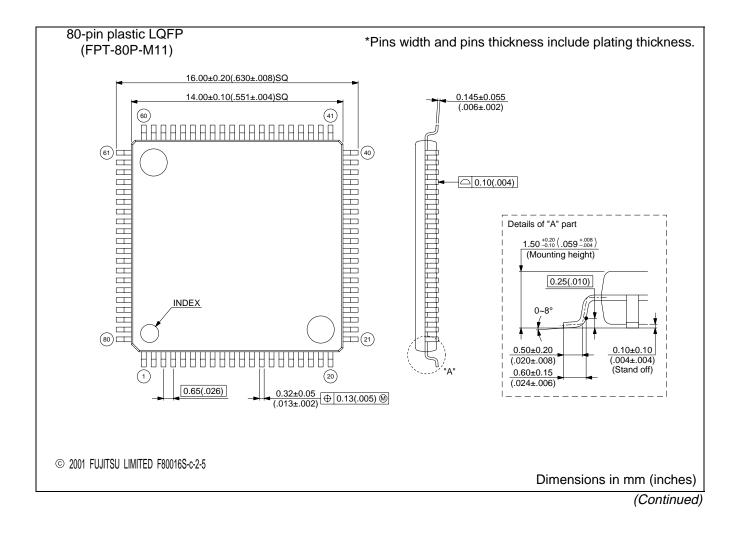
■ ORDERING INFORMATION

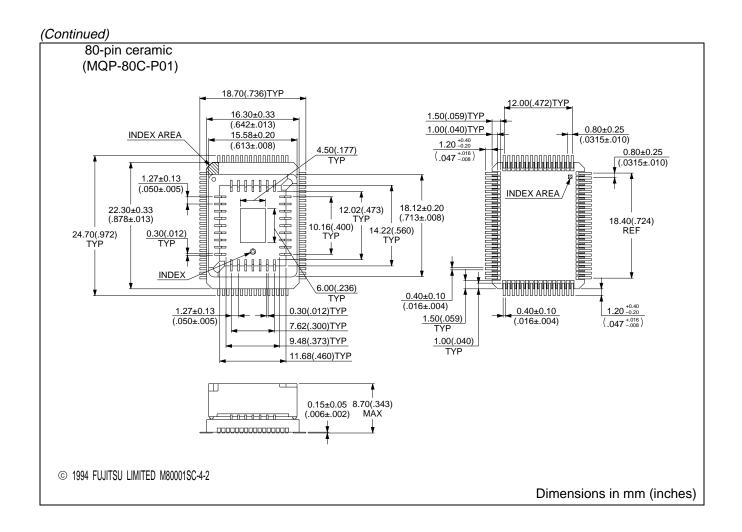
Part number	Package	Remarks
MB89567APFV MB89567ACPFV MB89P568PFV-101	80-pin Plastic LQFP (FPT-80P-M05)	Without Booster Resistor divider
MB89567APFV MB89567ACPFV MB89P568PFV-102		With Booster
MB89567APF MB89567ACPF MB89P568PF-101	80-pin Plastic QFP (FPT-80P-M06)	Without Booster Resistor divider
MB89567APF MB89567ACPF MB89P568PF-102		With Booster
MB89567APFM MB89567ACPFM MB89P568PFM-101	80-pin Plastic LQFP (FPT-80P-M11)	Without Booster Resistor divider
MB89567APFM MB89567ACPFM MB89P568PFM-102		With Booster
MB89PV560CF-101	80-pin Ceramic MQFP (MQP-80C-P01)	Without Booster Resistor divider
MB89PV560CF-102		With Booster

PACKAGE DIMENSIONS









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